

168 pin 8 BYTE-BUFFERED DIMM (Continued)

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load IC	Package outline	Outward dimensions W×H×D (mm)	Contact Plating	Access time	Type No.
576M	8Mx72	3.3V±0.3V	M5M467800AJx9	Both sides	133.35×31.75×4.6	Au plating	60	MH8V72AWZJ-6
			M5M465800AJx9		133.35×31.75×4.6		70	MH8V72AWZJ-7
			M5M467805AJx9		133.35×31.75×4.6		60	MH8V724AWZJ-6
			M5M465805AJx9		133.35×31.75×4.6		70	MH8V724AWZJ-7
			M5M467400AJx18		133.35×25.4×8.6		60	MH8V725AWZJ-6
1152M	16Mx72	3.3V±0.3V	M5M467405AJx18	Both sides	133.35×25.4×8.6	Au plating	70	MH8V725AWZJ-7
							60	MH16V724AWJ-6
							50	MH16V724AWJ-5
							60	MH16V725AWJ-6
							50	MH16V725AWJ-5
							60	MH16V725AWJ-6

168 pin 8 BYTE-UNBUFFERED SDRAM DIMM

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load IC	Package outline	Outward dimensions W×H×D (mm)	Contact Plating	CLK cycle time	Type No.
64M	1Mx64	3.3V±0.3V	M5M4V16S40CTPx4	Both sides	133.35×25.4×3.9	Au plating	15	MH1S64CPG-15
72M	1Mx72		M5M4V16S40CTPx5		133.35×25.4×3.9		12	MH1S64CPG-12
128M	2Mx64		M5M4V16S30CTPx8	Single side	133.35×29.21×3.2		15	MH1S72CPG-15
144M	2Mx72		M5M4V16S30CTPx9		133.35×31.75×3.2		12	MH1S72CPG-12
256M	4Mx64		M5M4V16S30CTPx16	Both sides	133.35×29.21×3.9		15	MH2S64CBLD-15
288M	4Mx72	3.3V±0.3V	M5M4V16S30CTPx18		133.35×31.75×3.9	Au plating	12	MH2S64CBLD-12
			M5M4V16S20CTPx18		133.35×31.75×3.9		15	MH2S72CMD-15
							12	MH2S72CMD-12
							15	MH4S64CBMD-15
							12	MH4S64CBMD-12
							15	MH4S72CMD-15
							12	MH4S72CMD-12
							15	MH4S72CMA-15
							12	MH4S72CMA-12

144 pin 8 BYTE-S.O.DIMM

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load IC	Package outline	Outward dimensions W×H×D (mm)	Contact Plating	Access time	Type No.
64M	1Mx64	3.3V±0.3V	M5M4V18160CTPx4	Both sides	67.6×25.4×3.63	Au plating	60	MH1V64CXJJ-6
			M5M4V18165CTPx4		67.6×25.4×3.63		70	MH1V64CXJJ-7
128M	2Mx64		M5M4V17800CTPx8		67.6×25.4×3.63		60	MH1V645CXJJ-6
			M5M4V17805CTPx8		67.6×25.4×3.63		70	MH1V645CXJJ-7
256M	4Mx64		M5M465160ATPx4		67.6×25.4×3.63		60	MH2V64CZJJ-6
			M5M465160ATPx4		67.6×25.4×3.63		70	MH2V64CZJJ-7
			M5M465160ATPx4		67.6×25.4×3.63		60	MH2V645CZJJ-6
			M5M465160ATPx4		67.6×25.4×3.63		70	MH2V645CZJJ-7
			M5M465165ATPx4		67.6×25.4×3.63		50	MH4V644AXJJ-5
			M5M465165ATPx4		67.6×25.4×3.63		60	MH4V644AXJJ-6
						50	MH4V64AXJJ-5	
						60	MH4V64AXJJ-6	
						50	MH4V64AXJJ-5	
						60	MH4V64AXJJ-6	
						50	MH4V6445AXJJ-5	
						60	MH4V6445AXJJ-6	
						50	MH4V645AXJJ-5	
						60	MH4V645AXJJ-6	

144 pin 8 BYTE- SDRAM S.O.DIMM

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load IC	Package outline	Outward dimensions W×H×D (mm)	Contact Plating	CLK cycle time	Type No.
64M	1Mx64	3.3V±0.3V	M5M4V16S40CTPx4	Both sides	67.6×25.4×3.63	Au plating	15	MH1S64CXJJ-15
128M	2Mx64		M5M4V16S30CTPx8		67.6×25.4×3.63		12	MH1S64CXJJ-12
			M5M4V16S40CTPx8		67.6×31.75×3.63		15	MH2S64CZJJ-15
				12			MH2S64CZJJ-12	
				15			MH2S64CXJJ-15	
						12	MH2S64CXJJ-12	